PRODUCT / PROCESS CHANGE NOTIFICATION

| 1. PCN basic data | | |
|----------------------|------------|---|
| 1.1 Company | 577 | STMicroelectronics International N.V |
| 1.2 PCN No. | | ADG/22/13788 |
| 1.3 Title of PCN | | IPAK AI wire line relocation from Shenzhen to Tongfu Microelectronics (China) |
| 1.4 Product Category | , | Power MOSFET HV, IGBT |
| 1.5 Issue date | | 2022-11-22 |

| | 2. PCN Team |
|---------------------------|---------------------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | KRISZTINA NEMETH |
| 2.1.2 Phone | +49 89460062210 |
| 2.1.3 Email | krisztina.nemeth@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Maurizio GIUDICE,Angelo RAO |
| 2.1.2 Marketing Manager | Paolo PETRALI, Natale Sandro D'ANGELO |
| 2.1.3 Quality Manager | Vincenzo MILITANO |

| | 3. Change | |
|--------------|---|----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617) | |

| | 4. Description of change | |
|---|--|--|
| | Old | New |
| 4.1 Description | IPAK AI wire products are manufactured in Shenzhen (China) | IPAK AI wire products are manufactured in Tongfu Microelectronics (China) |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no impact | |

| | 5. Reason / motivation for change |
|----------------------|------------------------------------|
| 5.1 Motivation | IPAK Line Shenzhen (China) closure |
| 5.2 Customer Benefit | SERVICE CONTINUITY |

| | 6. Marking of parts / traceability of change |
|-----------------|--|
| 6.1 Description | By internal traceability and dedicated FG code |

| | 7. Timing / schedule |
|-------------------------------------|----------------------|
| 7.1 Date of qualification results | 2022-11-20 |
| 7.2 Intended start of delivery | 2023-03-27 |
| 7.3 Qualification sample available? | Upon Request |

| | 8. Qualification / Validation | | |
|--|-------------------------------|---------------|------------|
| 8.1 Description | 13788 Binder1.pdf | | |
| 8.2 Qualification report and qualification results | | Issue Date | 2022-11-22 |

9. Attachments (additional documentations)

13788 Public product.pdf 13788 IPAK AI wire line relocation from Shenzhen to TFME.pdf 13788 Binder1.pdf 13788 Comparison IPAK STS vs TFME.pdf

| 10. Affected parts | | | |
|-------------------------|-------------------------|--------------------------|--|
| 10. 1 Current | | 10.2 New (if applicable) | |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No | |
| STD5NM60-1 | STD5NM60-1 | | |
| | STU10NM60N | | |
| | STU13N60M2 | | |
| | STU13NM60N | | |
| | STU2NK100Z | | |
| | STU5N62K3 | | |
| | STU5N95K3 | | |
| | STU6N62K3 | | |
| | STU6N95K5 | | |
| | STU7N105K5 | | |
| | STU7NM60N | | |
| | STD2HNK60Z-1 | | |
| | STD2NK90Z-1 | | |
| | STU8N80K5 | | |

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